




Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2017-01-25
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	ADG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement			
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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard
Legal Statement	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STPS160AY	BNSR*Z25MD1V	A	ZA41	2017-01-25
Amount		UoM	Unit type	ST ECOPACK Grade
70.00		mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape
SOJ	4.3 x 2.77 x 2	2	J bend
Comment	Package: SMA		

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-20th June 2016				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	BNSR*Z25MD1V					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	1.143	mg	supplier	die	Silicon (Si)	7440-21-3		1.086	mg	950131	15514
				supplier	metallization	Aluminium (Al)	7429-90-5		0.007	mg	6124	100
				supplier	metallization	Titanium (Ti)	7440-32-6		0.001	mg	876	14
				supplier	metallization	Tungsten (W)	7440-33-7		0.002	mg	1750	29
				supplier	metallization	Nickel (Ni)	7440-02-0		0.005	mg	4374	71
				supplier	metallization	Gold (Au)	7440-57-5		0.005	mg	4374	71
				supplier	Passivation	Silicon Oxide	7631-86-9		0.007	mg	6124	100
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.001	mg	875	14
				supplier	back side metallization	Gold (Au)	7440-57-5		0.002	mg	1750	29
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.007	mg	6124	100
				supplier	polymer die coating	Durimide	proprietary		0.020	mg	17498	286
				Leadframe & Clip	Copper and its alloy	26.745	mg	supplier	alloy	Copper (Cu)	7440-50-8	
supplier	alloy	Zinc (Zn)	7440-66-6						0.001	mg	37	14
supplier	alloy	Iron (Fe)	7439-89-6						0.003	mg	112	43
supplier	alloy	Iron Phosphide (FeP)	26508-33-8						0.009	mg	337	129
Soft solder	Solder	2.833	mg	supplier	solder	Silver (Ag)	7440-22-4		0.071	mg	25061	1014
				supplier	solder	Tin (Sn)	7440-31-5		0.142	mg	50124	2029
				JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	2.620	mg	924815	37429
Encapsulation	Other inorganic materials	38.642	mg	supplier	mold compound	Amorphous Silica	7631-86-9		23.812	mg	616221	340171
				supplier	mold compound	Quartz	14808-60-7		7.728	mg	199990	110400
				supplier	mold compound	epoxy resin	25068-38-6		4.637	mg	119999	66243
				supplier	mold compound	phenolic resin	9003-35-4		2.318	mg	59987	33114
				supplier	mold compound	Bismuth trioxide	1304-76-3		0.027	mg	699	386
				supplier	mold compound	chlorine residue	7782-50-5		0.004	mg	102	57
Connections coating	Solder	0.637	mg	supplier	mold compound	Carbon black	1333-86-4		0.116	mg	3002	1657
				supplier	solder alloy	Tin (Sn)	7440-31-5		0.637	mg	1000000	9100